



Smart Buildings: Integrating BIM and Artificial Intelligence for New Challenges of Design

Guest Editors:

Dr. Lorusso Angelo

Department of Industrial
Engineering (DII), University of
Salerno, 84084 Salerno, Italy

Dr. Domenico Santaniello

Department of Industrial
Engineering, University of
Salerno, 84084 Fisciano, Italy

Dr. Sara Antinozzi

Department of Civil Engineering,
Università degli Studi di Salerno,
84084 Fisciano, Italy

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Message from the Guest Editors

At the heart of the innovation process, when Artificial Intelligence (AI) intersects with Building Information Modeling (BIM), lies the creation of tomorrow's building: a giant with intelligence and sustainability. The development of intelligent architecture is one of the most exciting areas of innovation in civil engineering and architecture. Indeed, the integration of BIM and AI represents the starting point for a new design season in which new solutions are offered to meet the design needs of the future. Additionally, much interest is focused on modern devices and sensors capable of real-time monitoring, gathering vast amounts of data that could lead to the construction of digital copies of existing buildings.

Their application is not limited to building construction but covers the entire life cycle, with challenges and new opportunities for data management, predictive analysis, and building conservation. Areas of interest include but are not limited to, computation and data processing, machine learning, deep learning, the Internet of Things, and Digital Twin implementation for Smart Buildings.





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Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo

Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
da Vinci 32, 20133 Milano, Italy

Message from the Editor-in-Chief

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Applied Sciences Editorial Office
MDPI, St. Alban-Anlage 66
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